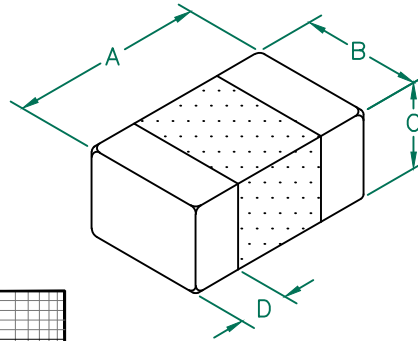


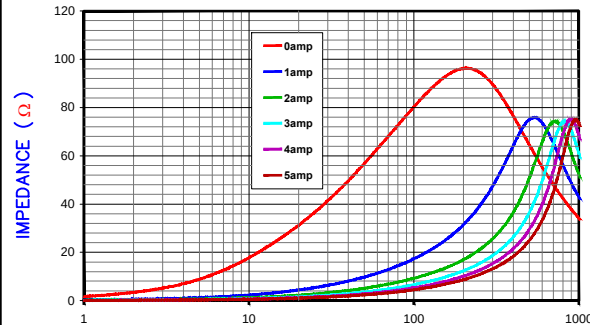
HI0805R800R-10

PHYSICAL DIMENSIONS:

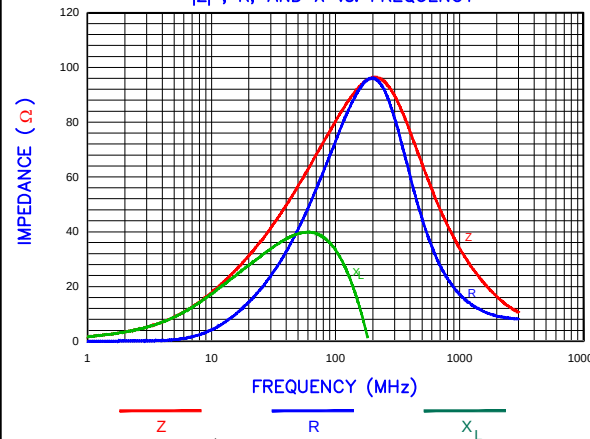
A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]



Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS

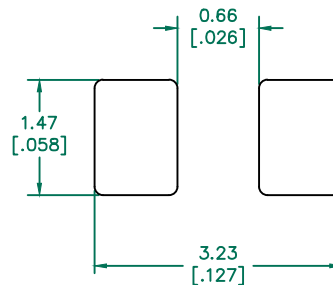


FREQUENCY (MHz)
[Z], R, AND X vs. FREQUENCY



AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3796

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763
[.030] to this dimension.)

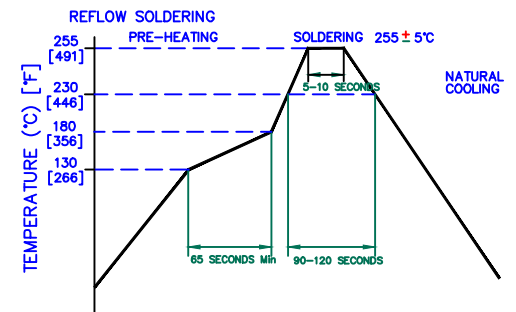
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	80	
Minimum	60	
Maximum	100	0.010 5000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REE, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. CONTINUOUS CURRENT RATING OF 5000 mA.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



RoHS

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
				Laird			
E	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER HI0805R800R-10			
D	CHANGE TO PAPER TAPE	03/03/10	JUN	REV	PART TYPE:	DRAWN BY:	
C	UPDATE COMPANY LOGO	06/15/09	JRK	E	CO-FIRE	TMB	
B	UPDATE COMPANY LOGO	01/17/08	JRK	DATE	04/02/04	SCALE	NTS
A	ORIGINAL DRAFT	04/02/04	TMB	CAD #	HI0805R800R-10-E	TOOL #	-
REV	DESCRIPTION	DATE	INT	SHEET: 1 of 1			